Circuit connecting material, film-like circuit connecting material using the same, circuit member connecting structure, and method of producing the same

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The present invention is a circuit connecting material used for the mutual connection of a circuit member in which electrodes and insulating layers are formed adjacent to each other on the surface of a board, and a circuit member in which electrodes and insulating layers are formed adjacent to each other on the surface of a board, with the edge parts and of the insulating layers being formed with a greater thickness than the electrodes on the basis of the main surfaces, wherein this circuit connecting material contains a bonding agent composition and conductive particles that have a mean particle size of 1 [mu]m or greater but less than 10 [mu]m and a hardness of 1.961 to 6.865 GPa,; and this circuit connecting material exhibits a storage elastic modulus of 0.5 to 3 GPa at 40 DEG C and a mean coefficient of thermal expansion of 30 to 200 ppm/ DEG C at from 25 DEG C to 100 DEG C when subjected to the curing treatment.

Fig.1